







160V NPN HIGH VOLTAGE TRANSISTOR PowerDl[®]5

Features and Benefits

- 43% smaller than SOT223; 60% smaller than TO252
- Maximum height just 1.1mm
- Rated up to 2.25W
- $BV_{CEO} > 160V$
- $I_{C(cont)} = 0.6A$
- Lead Free, RoHS Compliant (Note 1)
- Halogen and Antimony Free, "Green" Device (Note 2)
- Qualified to AEC-Q101 Standards for High Reliability

Top View

Applications

Telecom line driver

Mechanical Data

- Case: PowerDI[®]5
- Case Material: Molded Plastic, "Green" Molding Compound. UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminals: Finish Matte Tin annealed over Copper leadframe. Solderable per MIL-STD-202, Method 208 @3
- Weight: 0.093 grams (approximate)





Bottom View



Device Schematic



Pin-out diagram

Ordering Information (Note 3)

Product	Marking	Reel size (inches)	Tape width (mm)	Quantity per reel
DXT5551P5-13	DXT5551	13	16	5,000

1. No purposefully added lead. Notes:

2. Halogen and Antimony Free. Diodes Inc's "Green" Policy can be found on our website at http://www.diodes.com

3. For packaging details, go to our website at http://www.diodes.com

Marking Information



DXT5551 = Product Type Marking Code DII = Manufacturers' Code Marking K = Factory Designator YYWW = Date Code Marking YY = Last Two Digits of Year (ex: 09 for 2009) WW = Week code (01 - 53)

PowerDI is a registered trademark of Diodes Incorporated. DXT5551P5 1 of 7 www.diodes.com Document number: DS32066 Rev. 3 - 2





Maximum Ratings @T_A = 25°C unless otherwise specified

Characteristic	Symbol	Value	Unit
Collector-Base Voltage	V _{CBO}	180	V
Collector-Emitter Voltage	V _{CEO}	160	V
Emitter-Base Voltage	V _{EBO}	6	V
Continuous Collector Current	Ιc	600	mA

Thermal Characteristics @TA = 25°C unless otherwise specified

Characteristic	Symbol	Value	Unit
Power Dissipation (Note 4)	PD	2.25	W
Thermal Resistance, Junction to Ambient Air (Note 4)	$R_{ heta JA}$	55.5	°C/W
Power Dissipation (Note 5)	PD	1.28	W
Thermal Resistance, Junction to Ambient Air (Note 5)	$R_{ heta JA}$	97.4	°C/W
Power Dissipation (Note 6)	PD	0.7	W
Thermal Resistance, Junction to Ambient Air (Note 6)	$R_{ heta JA}$	179	°C/W
Thermal Resistance, Junction to Collector Terminal	$R_{ extsf{ heta}JT}$	30	°C/W
Operating and Storage Temperature Range	T _J , T _{STG}	-55 to +150	٥°

 Device mounted on 1.6mm FR-4 PCB, single sided 2 oz. copper, collector pad dimensions 50mm x 50mm.
Device mounted on 1.6mm FR-4 PCB, single sided 1 oz. copper, collector pad dimensions 25mm x 25mm. Notes:

6. Device mounted on 1.6mm FR-4 PCB, single sided 1 oz. copper, minimum recommended pad layout.





Thermal Characteristics







Electrical Characteristics @T_A = 25°C unless otherwise specified

Characteristic	Symbol	Min	Тур	Max	Unit	Test Condition
Collector-Base Breakdown Voltage	BV _{CBO}	180	270	-	V	I _C = 100μA
Collector-Emitter Breakdown Voltage (Note 7)	BV _{CEO}	160	200	-	V	$I_{\rm C} = 1 {\rm mA}$
Emitter-Base Breakdown Voltage	BV _{EBO}	6.0	7.85	-	V	$I_E = 10 \mu A$
Collector Cutoff Current	I _{CBO}	-	<1 _	50 50	nA μA	V _{CB} = 120V V _{CB} = 120V, T _A = 100°C
Collector-Emitter Saturation Voltage (Note 7)	V _{CE(sat)}	-	65 115	150 200	mV mV	$I_C = 10mA$, $I_B = 1mA$ $I_C = 50mA$, $I_B = 5mA$
Base-Emitter Saturation Voltage (Note 7)	V _{BE(sat)}	-	760 840	1000 1200	mV mV	$I_{C} = 10mA$, $I_{B} = 1mA$ $I_{C} = 50mA$, $I_{B} = 5mA$
DC Current Gain (Note 7)	hFE	80 80 30	130 145 65	_ 250 _	_	$V_{CE} = 5V, I_C = 1mA$ $V_{CE} = 5V, I_C = 10mA$ $V_{CE} = 5V, I_C = 50mA$
Transition Frequency	fT	_	130	I	MHz	$V_{CE} = 10V, I_C = 10mA,$ f = 100MHz
Output Capacitance (Note 7)	C _{obo}	-	-	6	pF	$V_{CB} = 10V$, f = 1MHz
Delay Time	t _(d)	_	95	-	ns	
Rise Time	t _(r)	-	64	-	Ns	$V_{CC} = 510V, I_{C} = 10mA,$
Storage Time	t _(s)	-	1256	1	ns	$I_{B1} = I_{B2} = 1mA$
Delay Time	t _(f)	_	140	-	ns	

Notes: 7. Pulse Test: Pulse width ≤300µs. Duty cycle ≤2.0%.





Typical Characteristics







Package Outline Dimensions



Suggested Pad Layout



Dimensions	Value (in mm)
С	1.840
G	0.852
Х	3.360
X1	1.390
Y	4.860
Y1	1.400





IMPORTANT NOTICE

DIODES INCORPORATED MAKES NO WARRANTY OF ANY KIND, EXPRESS OR IMPLIED, WITH REGARDS TO THIS DOCUMENT, INCLUDING, BUT NOT LIMITED TO, THE IMPLIED WARRANTIES OF MERCHANTABILITY AND FITNESS FOR A PARTICULAR PURPOSE (AND THEIR EQUIVALENTS UNDER THE LAWS OF ANY JURISDICTION).

Diodes Incorporated and its subsidiaries reserve the right to make modifications, enhancements, improvements, corrections or other changes without further notice to this document and any product described herein. Diodes Incorporated does not assume any liability arising out of the application or use of this document or any product described herein; neither does Diodes Incorporated convey any license under its patent or trademark rights, nor the rights of others. Any Customer or user of this document or products described herein in such applications shall assume all risks of such use and will agree to hold Diodes Incorporated and all the companies whose products are represented on Diodes Incorporated website, harmless against all damages.

Diodes Incorporated does not warrant or accept any liability whatsoever in respect of any products purchased through unauthorized sales channel. Should Customers purchase or use Diodes Incorporated products for any unintended or unauthorized application, Customers shall indemnify and hold Diodes Incorporated and its representatives harmless against all claims, damages, expenses, and attorney fees arising out of, directly or indirectly, any claim of personal injury or death associated with such unintended or unauthorized application.

Products described herein may be covered by one or more United States, international or foreign patents pending. Product names and markings noted herein may also be covered by one or more United States, international or foreign trademarks.

LIFE SUPPORT

Diodes Incorporated products are specifically not authorized for use as critical components in life support devices or systems without the express written approval of the Chief Executive Officer of Diodes Incorporated. As used herein:

- A. Life support devices or systems are devices or systems which:
 - 1. are intended to implant into the body, or
 - 2. support or sustain life and whose failure to perform when properly used in accordance with instructions for use provided in the labeling can be reasonably expected to result in significant injury to the user.
- B. A critical component is any component in a life support device or system whose failure to perform can be reasonably expected to cause the failure of the life support device or to affect its safety or effectiveness.

Customers represent that they have all necessary expertise in the safety and regulatory ramifications of their life support devices or systems, and acknowledge and agree that they are solely responsible for all legal, regulatory and safety-related requirements concerning their products and any use of Diodes Incorporated products in such safety-critical, life support devices or systems, notwithstanding any devices- or systems-related information or support that may be provided by Diodes Incorporated. Further, Customers must fully indemnify Diodes Incorporated and its representatives against any damages arising out of the use of Diodes Incorporated products in such safety-critical, life support devices or systems.

Copyright © 2010, Diodes Incorporated

www.diodes.com